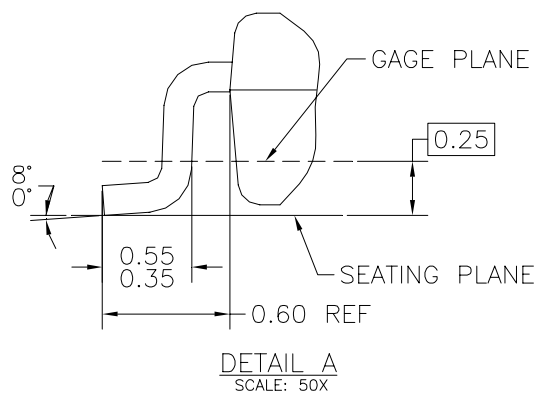
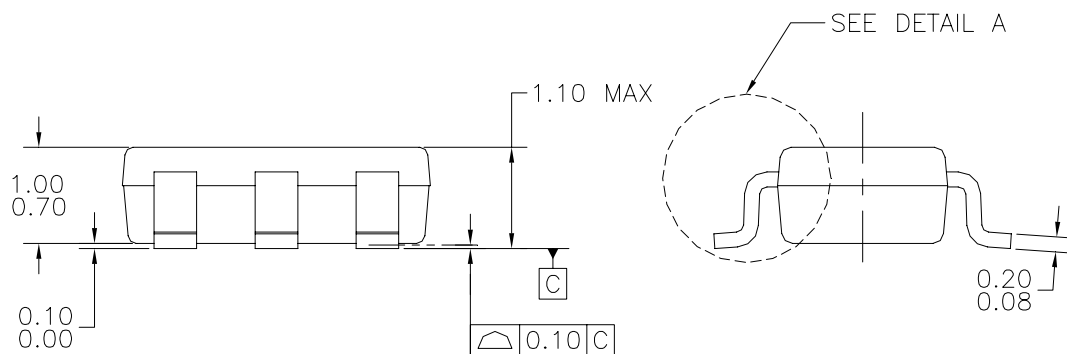


参考資料

Figure 1: Dimensional drawing of a 3x3 array of microvias. The drawing shows a top view of the array with dimensions in millimeters. The array is 3.00 mm wide and 2.80 mm high. The center-to-center spacing between vias is 1.90 mm. The diameter of each microvia is 0.20 mm. The thickness of the copper layer is 0.030 mm. The thickness of the prepreg layer is 0.50 mm. The thickness of the core layer is 1.50 mm. The thickness of the substrate is 2.60 mm. The drawing also shows a cross-section of the array, indicating the symmetry of the structure. The cross-section shows the microvia structure with a 1.00 mm minimum height. The cross-section also shows the 0.70 mm minimum spacing between the vias. The drawing includes a table of dimensions: 0.20 (M), C, A, B. The drawing is labeled "LAND PATTERN RECOMMENDATION".

LAND PATTERN RECOMMENDATION



A) THIS PACKAGE CONFORMS TO JEDEC MO-193.
VAR. AA, ISSUE C, DATED JANUARY 2000.

B) ALL DIMENSIONS ARE IN MILLIMETERS.

October 2006, Rev. B